

IMBA-Q87B

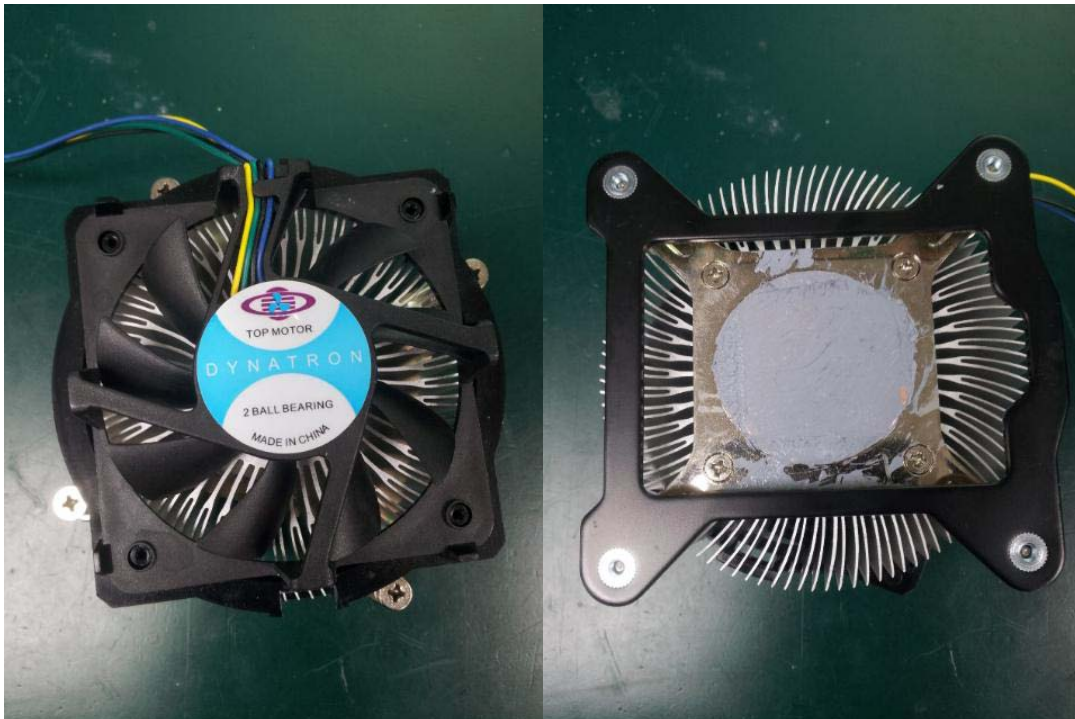
Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>After compared with component datasheet, there were 3 components' surface temperature located in marginal pass criteria.</u>				
	Test Result Summary				
	Critical	Major	Minor	Enhancement	
Defect Found	0	0	0	3	
Defect Unsolved	0	0	0	3	

Issue date	Approval	Test Engineer
2015 / 05 / 21	KJ Wang	Juno Cheng

Sample Configuration & Quantity Under Test

- Model name : IMBA-Q87B A1.00
- CPU Board : IMBA-Q87B A1.00
- CPU : Intel Core i7- 4770 Processor(8M Cache, 3.4GHz up to 3.90GHz) 84W
- Memory : Transcend 8GB * 2 / DDR3 1600 U / SEC K4B4G0846B
Transcend 8GB * 2 / DDR3 1600 U / ELPIDA 1226R6JH420
- 2.5" SATA HDD : WD WD5000LPVT 500GB
- BIOS : IMBA-Q87B R0.3 (AQ87BM03)(03/24/2014)
- Test Software : Windows 7 / Run PassMark Burn In Test 7.1 Pro
- Power : ATX Power
- CPU Cooler :



Thermal Image Analysis

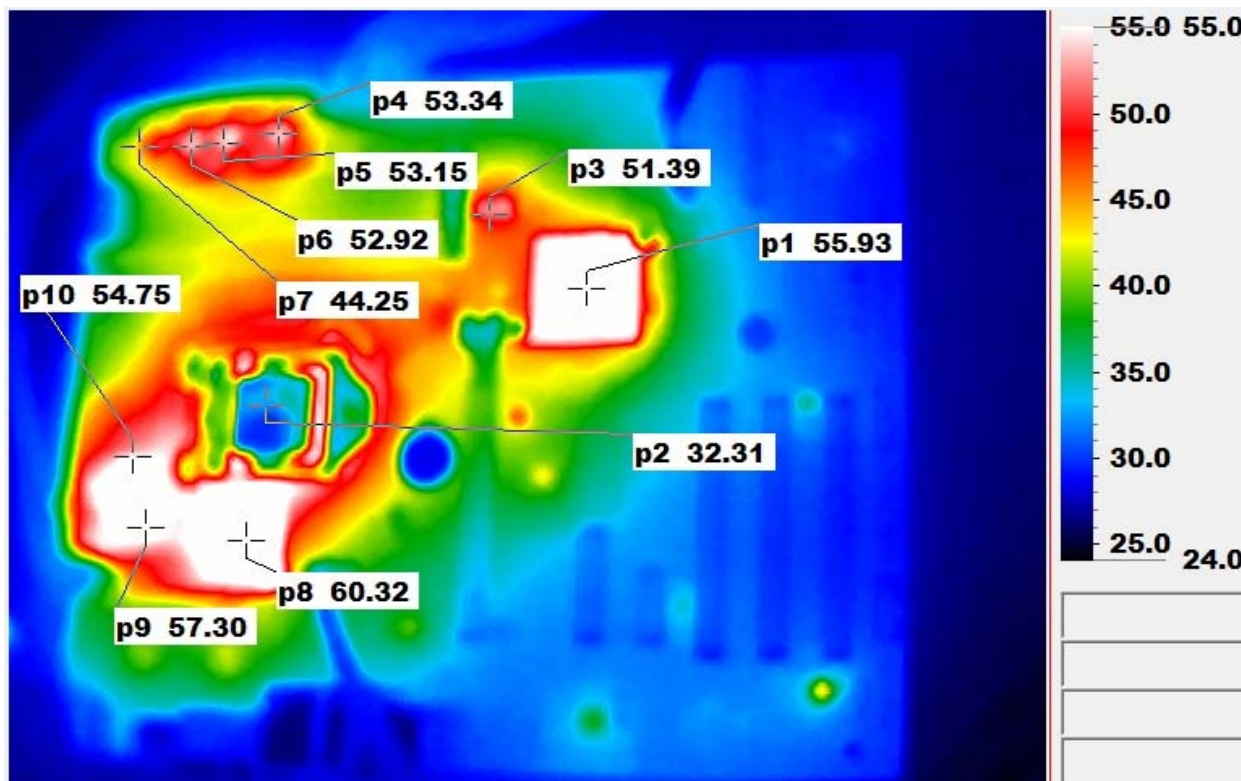
1. Test Date: 2015-05-21
2. Test Product: IMBA-Q87B
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
 - 4.1. 40 Channel Thermal Recorder:
 - 4.1.1 YOKOGAWA Inc,
 - 4.2.2 Model: DA100-13-1D
 Date of Calibration: 2014/10/01
 Serial Number: 12A323190
 - 4.2. IR Scanner: Infrared Camera
 - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
 - 4.2.2 Model: Thermo GEAR G100W2-D
 Date of Calibration: 2014/12/18
 Serial Number: 1051444
5. Test Condition:

Test by DA-100: 25.0°C with Heat Sink + FAN (Full speed)
6. Take Picture Time:

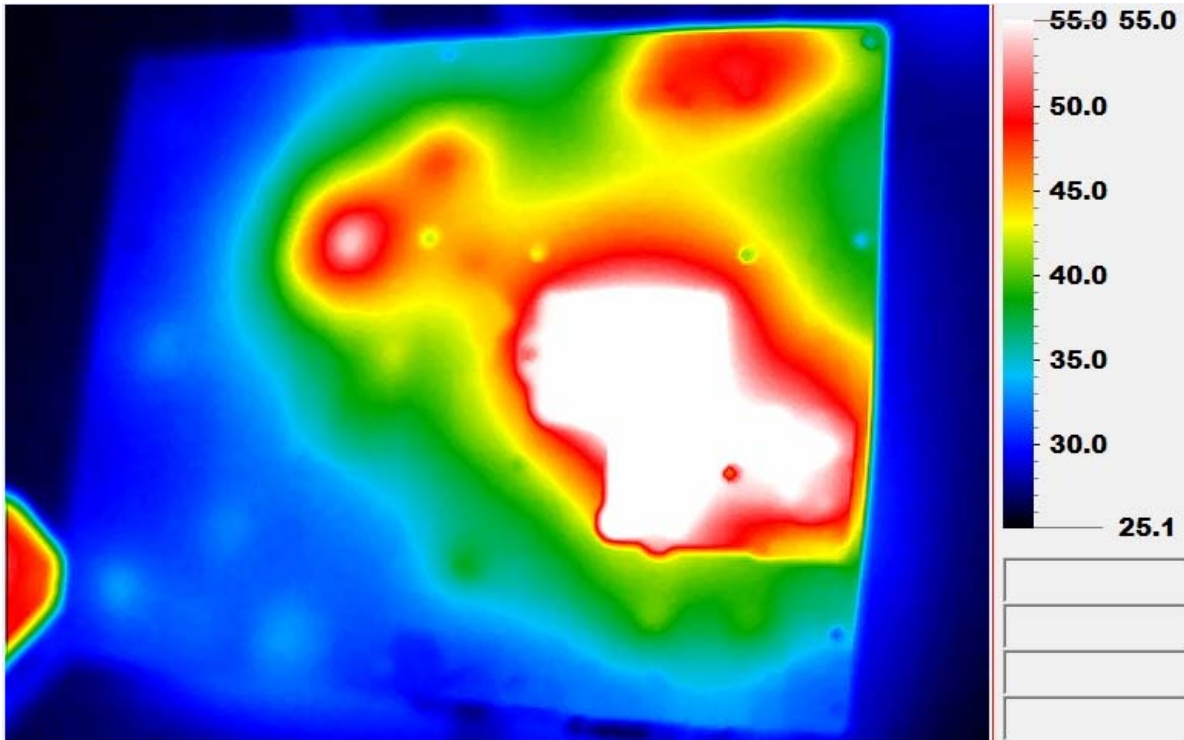
After power on 2 hours

Temperature Profile Test:

Component Side:

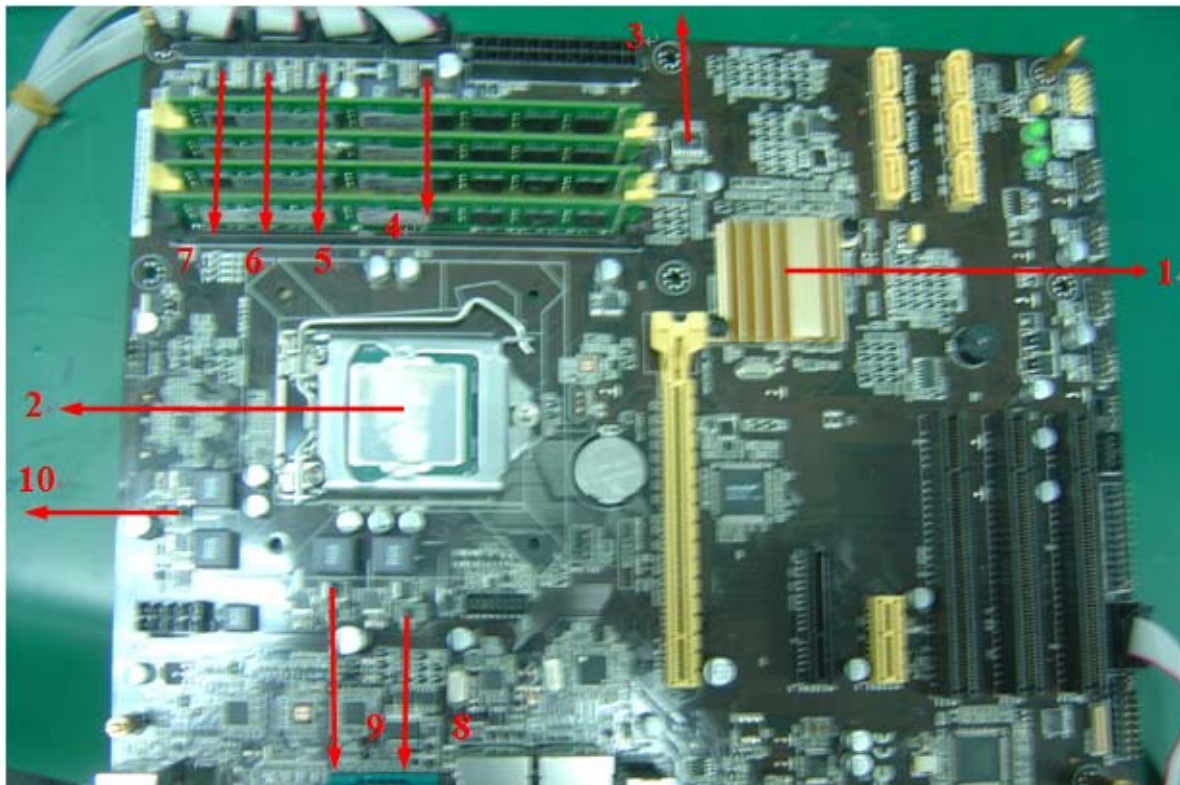


Back Side



Terminal Recorder :

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.0°C	60°C	
1	SU1	C.S FCBGA708//INTEL 929132/DH82Q87/SR173	104	41.9	76.9	
2	CPU	Intel Haswell DT (LGA1150) 86W CPU	73.78	37.8	72.8	Note 3
3	PU4	OP AMP. AS324MTR-E1 SOIC-14//AAC	100	35.9	70.9	
4	OU11	INTERFACE AZ75232GTR-E1//BCD TSSOP-20	100	58.3	93.3	Note 3
5	OU13	INTERFACE AZ75232GTR-E1//BCD TSSOP-20	100	55.5	90.5	Note 3
6	OU12	INTERFACE AZ75232GTR-E1//BCD TSSOP-20	100	53.2	88.2	
7	OU10	INTERFACE AZ75232GTR-E1//BCD TSSOP-20	100	52.4	87.4	
8	PU9	MOSFET DRIVER IC RT9611AGQW//RICHTEK WDFN-8L	100	50.5	85.5	
9	PQ838	N-MOSFET PH2530AL SOT-669//NXP	105	40.7	75.7	
10	PQ834	N-MOSFET PH2530AL SOT-669//NXP	105	46.8	81.8	
11	-	Memory chipset – 1	95	30.7	65.7	
12	-	Memory chipset – 2	95	36.9	71.9	

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- Fail : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
- Margin : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- Pass : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.

4. Defect NO. : [BUL1407QED01](#)